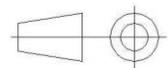
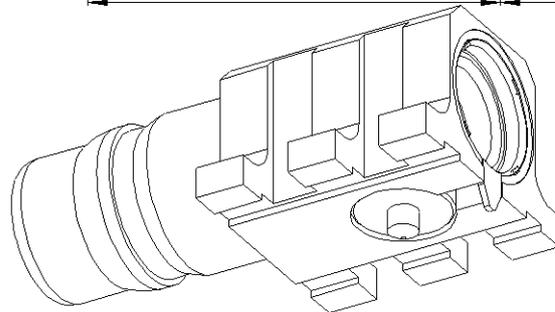
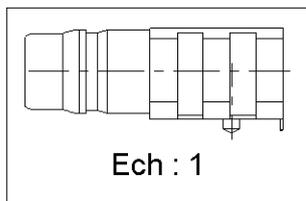
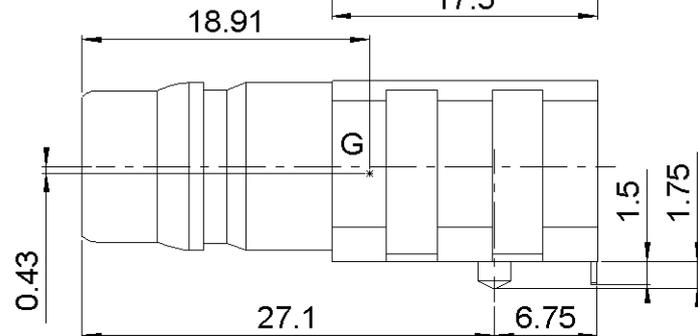
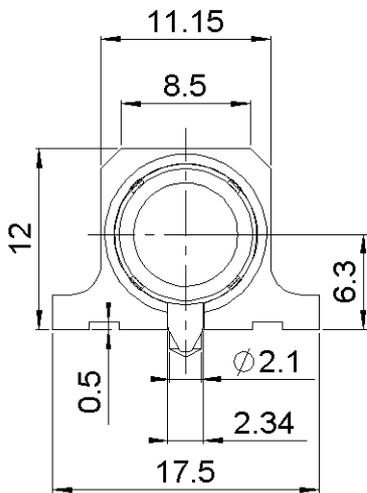
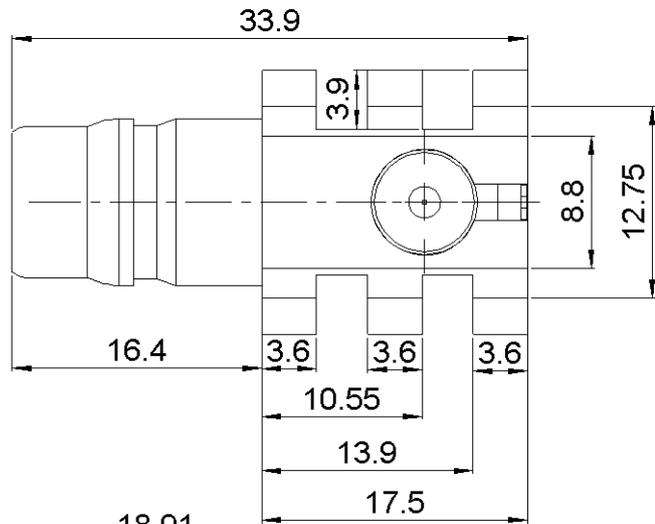
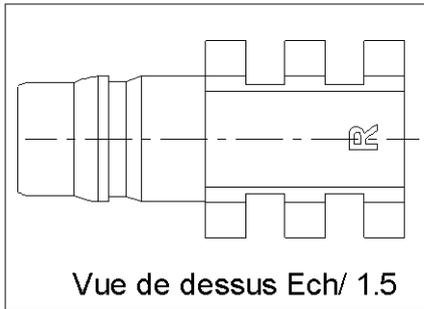


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All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (µm)
Body	BRASS	NPGR
Center contact	BERYLLIUM COPPER	NPGR
Outer contact	-	-
Insulator	PTFE	-
Gasket	-	-
Others parts	BRASS	GOLD OVER COPPER
-	-	-
-	-	-

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PACKAGING

Standard	Unit	Other
100	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance		50	Ω	
Frequency		0-6*	GHz	
VSWR	1.05	+	0.0250	x F(GHz) Maxi
Insertion loss			0.048	√F(GHz) dB Maxi
RF leakage	-		**90	- F(GHz) dB Maxi
Voltage rating			500	Veff Maxi
Dielectric withstanding voltage			1500	Veff mini
Insulation resistance			5000	MΩ mini

ENVIRONMENTAL

Operating temperature	-55/+125°	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

MECHANICAL CHARACTERISTICS

Center contact retention				
Axial force – Mating End		18	N mini	
Axial force – Opposite end		18	N mini	
Torque		NA	N.cm mini	
Recommended torque				
Mating		NA	N.cm	
Panel nut		NA	N.cm	
Mating life		100	Cycles mini	
Weight		21.1000	g	

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:

Others:

***usable 0-11GHz(ligne adaptée seulement)**

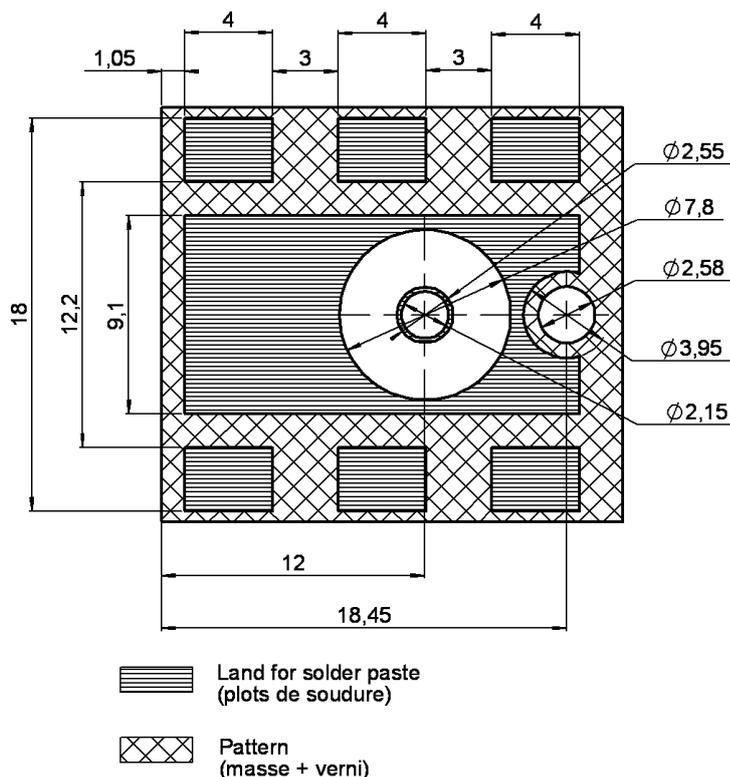
****RF Leakage : -80dB min 3<F<6GHz**

*****PIM3: -112 dBm (2 x 20W at 1.8GHz)**

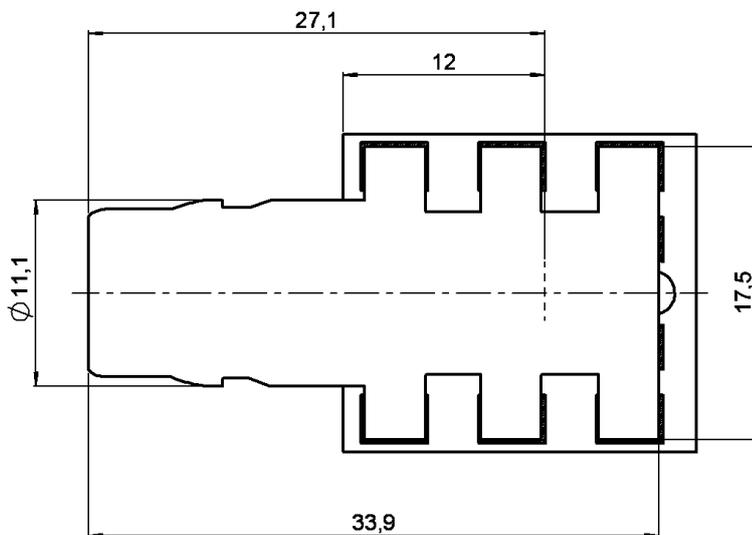
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QN SERIES - INFORMATIONS

Coplanar line : pattern and signal are on the same side . Thickness of PCB : .063(1.6mm)
The material of PCB is the epoxy resin of glass fabrics bacs . (Er = 4.8) . The solder resist should be printed except for the land pattern on the PCB .



SHADOW OF QN RECEPTACLE FOR VIDEO CAMERA

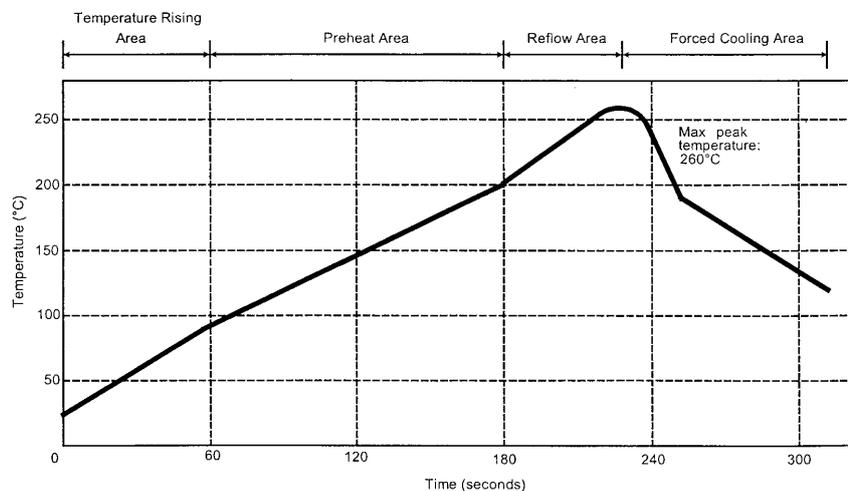


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SOLDER PROCEDURE

1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application.
We recommend a low residue flux.
We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
Video camera is preferred to check the positioning of the compnent. Adhesive agents are forbidden on the receptacle.
3. Soldering by infra-red reflow.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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